

1860 陶瓷 贴片式发光二极管

特点 (Characteristics) :

* 外观尺寸 (L/W/H) :1.8*6.0*0.7mm

Appearance dimension (L / w / h): 1.8 x6.0 *0.7mm

* 发光颜色及胶体: 白光/黄色雾状

Luminous color and colloid: white /yellow fog

* 冷光源, 接触安全

Cool beam, safe to the touch

* 倒装芯片工艺

Flip Chip Technology

* 环保产品, 符合 ROHS 要求

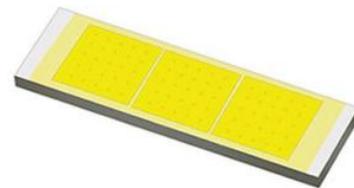
Environmental protection products meet ROHS requirements

* 湿气敏感性等级 (MSL) :3 级

Moisture sensitivity level (MSL) : 3 levels

* 低电压直流工作

Low voltage DC operated



模型图仅供参考

应用领域 (Product application) :

* 汽车照明

Automotive lighting

* 电动车摩托车照明

Electric motorcycle lighting

* 外部和内部照明应用

Exterior and interior lighting applications

* 工业与商业照明

Industrial and Commercial Lighting



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电性参数

Electrical Characteristics

极限参数 (Ta=25°C) Absolute Maximum Rating (ta=25 °C)

| 项目 Item | 符号 Symbol | 最大额定值 Absolute Maximum Rating | 单位 Unit |
|------------------------------|--------------|----------------------------------|------------|
| 功率消耗 Power Dissipation | PD | 15 | W |
| 正向电流 Forward Current | IF | 1500 | mA |
| 正向峰值电流 Pulse Forward Current | IFP | 2000 | mA |
| 工作温度 Operating Temperature | Topr | -40 TO +135°C | °C |
| 贮藏温度 Storage Temperature | Tstf | -40 TO +85°C | °C |
| 焊接温度 Soldering Temperature | Tsld | Reflow Soldering:260°C for 3sec | |

- 注: 1. 辐射通量测量公差: ±10%; Radiant flux measurement tolerance:±10%
 2. 正向电压测量公差: ±3%; Forward voltage measurement tolerance:±3%
 3. 峰值波长测量公差: ±3nm; Peak wavelength measurement tolerance:±3nm
 4. 1/10 占空比, 0.1ms 脉冲宽度; 1/10 Duty Cycle,0.1ms Pulse Width

光电参数 (Ta=25°C) Optical-electrical parameter (ta=25 °C)

| 参数名称 Parameter | 符号 Symbol | 测试条件 Condition | 数值 Value | | | 单位 Unit |
|--------------------------------|--------------|-------------------|-----------|-----------|-----------|------------|
| | | | 最小 Min | 典型 Typ | 最大 Max | |
| 正向电压 Forward Voltage | VF | IF=1000mA | 8.7 | - | 9.6 | V |
| 光通量 Luminous flux | Φ | IF=1000mA | 1000 | - | 1500 | lm |
| 色温 Color temperature | TC | IF=1000mA | 5500 | - | 7000 | K |
| 显色指数 Color rendering index | Ra | IF=1000mA | - | 70 | - | - |
| 全视角 Viewing angle | 2θ 1/2 | IF=1000mA | - | 120 | - | Deg |
| 晶片结温 Junction temperature | TJ | IF=1000mA | - | - | 145 | °C |
| 热阻 Thermal resistance | Rthj-s | IF=1000mA | - | - | 3-5 | °C/W |
| 抗静电能力 ESD Sensitivity (HBM) | ESD | IF=1000mA | 2000V | | | |

亮度分档:

Brightness grading:

| 代码 Code | 最小值 Min | 最大值 Max | 单位 Unit | 测试条件 Test conditions |
|------------|------------|------------|------------|-------------------------|
| N5 | 1000 | 1100 | LM | IF=1000mA |
| N6 | 1100 | 1200 | | |
| N7 | 1200 | 1350 | | |
| N8 | 1350 | 1500 | | |

电压分档:

Voltage grading:

| 代码 Code | 最小值 Min | 最大值 Max | 单位 Unit | 测试条件 Test conditions |
|------------|------------|------------|------------|-------------------------|
| S13-3 | 8.7 | 9.0 | V | IF=1000mA |
| S13-4 | 9.0 | 9.3 | | |
| S13-5 | 9.3 | 9.6 | | |

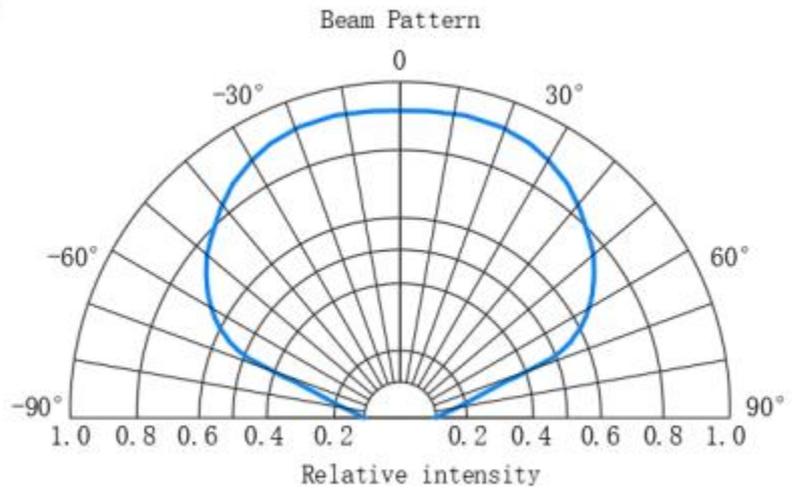
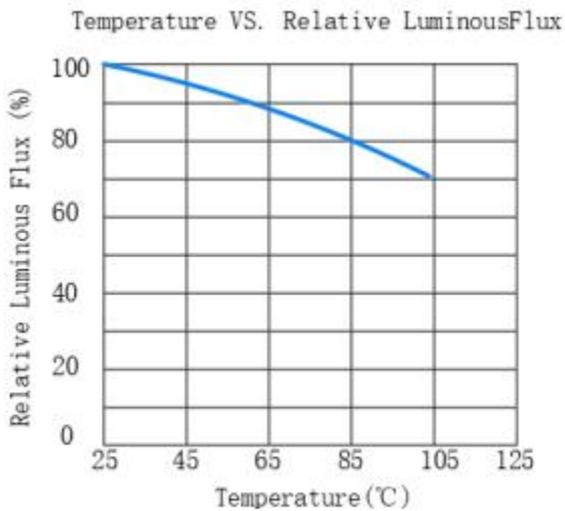
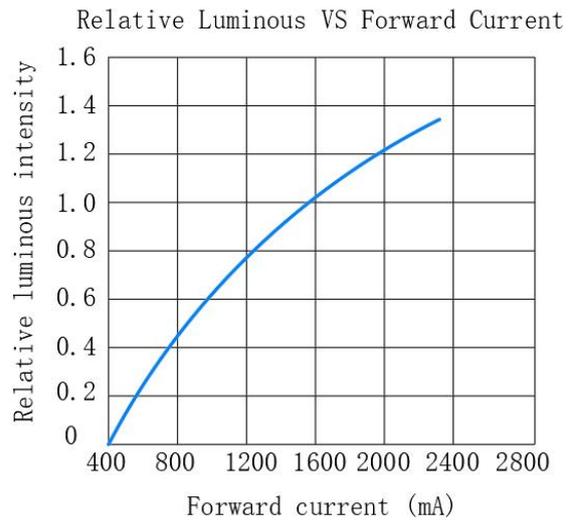
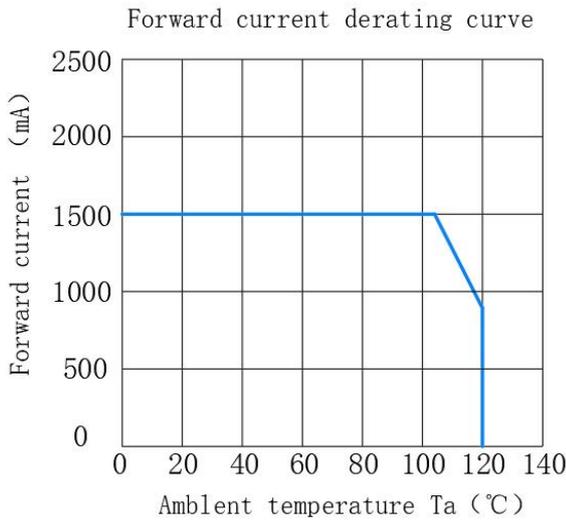
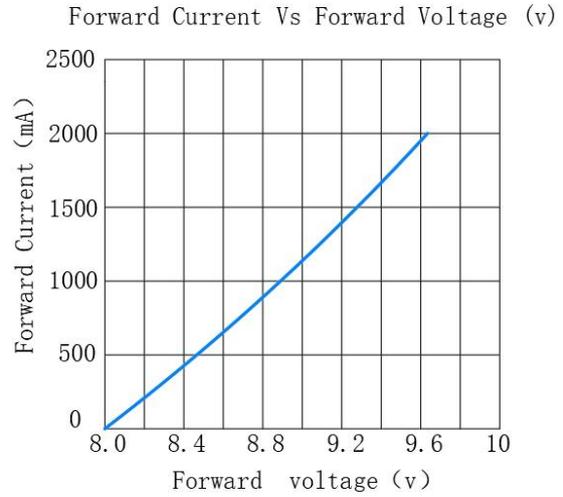
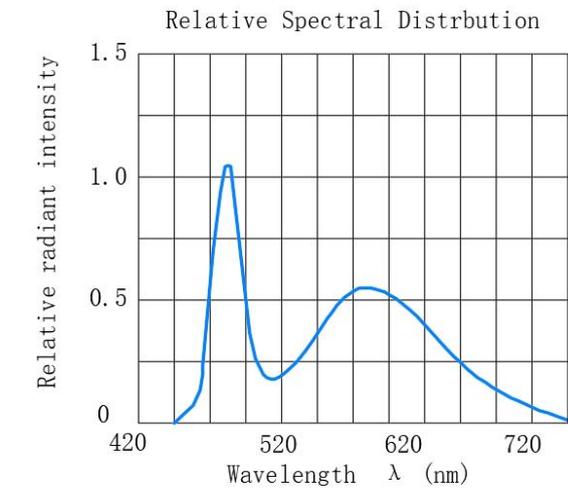
色温分档:

Color temperature division:

| 代码 Code | 最小值 Min | 最大值 Max | 单位 Unit | 测试条件 Test conditions |
|------------|------------|------------|------------|-------------------------|
| UW7-10 | 5500 | 6000 | K | IF=1000mA |
| UW9-10 | 6000 | 6500 | | |
| UW11-10 | 6500 | 7000 | | |

典型特性曲线

Typical Characteristics Curves



注：如无另外注明，测试环境温度为 $25 \pm 5^\circ\text{C}$ / Note: If not otherwise indicated the test environment temperature is $25 \pm 5^\circ\text{C}$

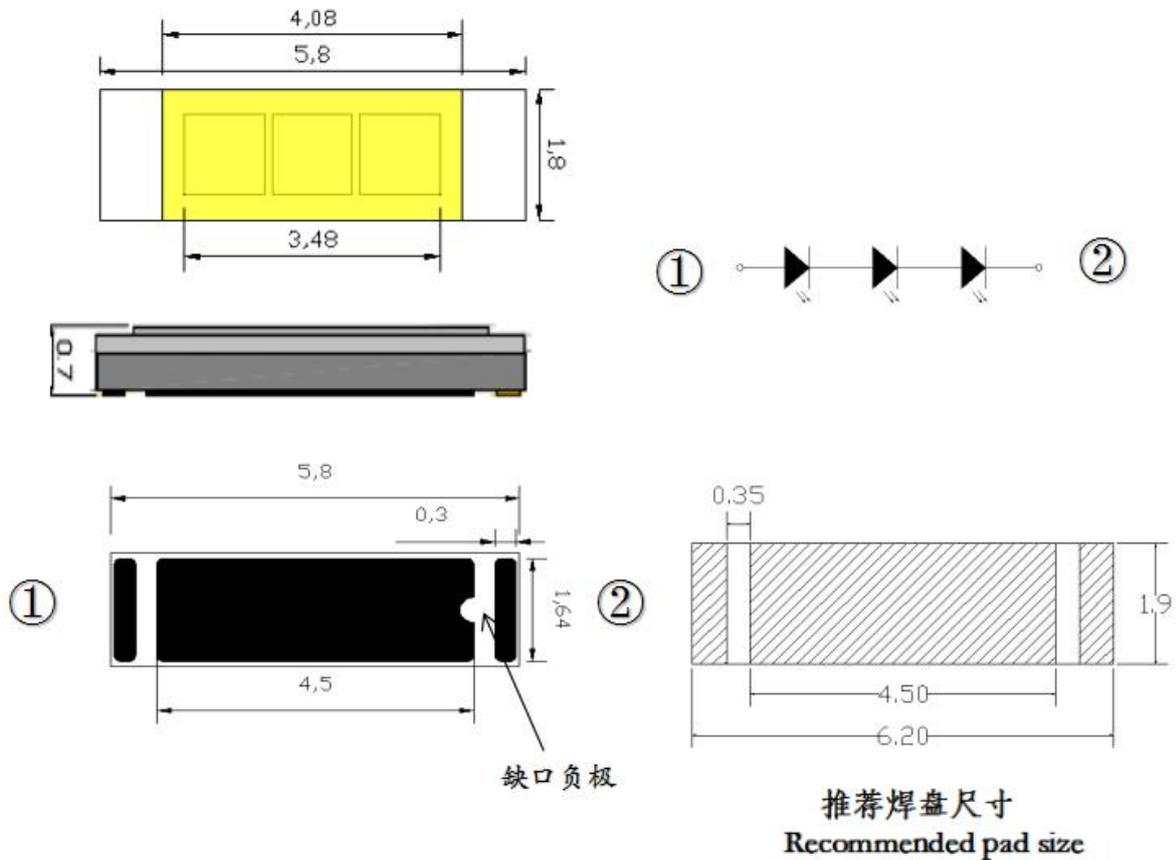
可靠性试验

Reliability Test Items And Conditions

| 类别 Class | 测试项目 Test item | 测试环境 Testing environment | 测试时间 Testing time | 参考标准 Reference standard |
|--------------------------------------|--|--|---|---|
| 耐久性测试 Endurance test | 工作寿命 Working life | 室温条件下以最大额定电流持续点亮： 以 1500mA 测试 (Continuous lighting at the maximum rated current at room | 1000 小时 1000 hours (-24 小时,+72 小时) (-24hours, +72hours | MIL-STD-750D:1026 MIL-STD-883D:1005 JIS C 7021:B-1 |
| | 高温高湿储存 High temperature and high humidity storage | IR-Reflow In-Board, 2 Times 环境温度Ta= 85±5℃, 相对湿度RH= 90~95% | 240 小时 240hours (± 2 小时) (± 2hours) | MIL-STD-202F:103B JIS C 7021:B-11 |
| | 高温储存 High-temperatur e storage | 环境温度Ta= 85±5℃ | 1000 小时 1000 hours (-24小时 +72小时) | MIL-STD-883D:1008 JIS C 7021:B-10 |
| | 低温储存Low temperature | 环境温度 Ta= -40±5℃ | (-24hours+72hours) | JIS C 7021:B-12 |
| 环境测试 Environme ntal testing | 冷热循环 Cold and hot cycle | 105℃ ~ 25℃ ~ -55℃ ~ 25℃ 30mins 5mins 30mins 5mins | 100 次 循环 100 Circles | MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010 |
| | 冷热冲击 Hot and cold impact | IR-Reflow In-Board, 2 Times; 100± 5℃ ~ -40℃ ± 5℃; 20mins ; 20mins | 100 次 循环 100 Circles | MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1011 |
| | 抗锡试验 Anti-tin test | 焊锡温度 T. sol= 260 ± 5℃ | 10 ± 1secs 2 次 2times | MIL-STD-202F:210A MIL-STD-750D:2031 |
| | 红外回流焊 有铅制程 Infrared reflowwelding There is lead process | 升温速度 heat up speed(183℃到最高值) : 最 大 3℃/秒; 维持温度 keep temperature 在 125(±25)℃: 不超过 120 秒; 维持温度 keep temperature 在 183℃以上: 60-150 秒 最高温度限制范围maximum temperature: 235℃ +5/-0℃; 维持keep在235℃+5/-0℃时间: 10-15 秒; 降温速度cooling rate: 最大6℃/秒 | ----- | MIL-STD-750D:2031.2 J-STD-020C |
| | 红外回流焊 无铅制程 Infrared reflow welding Lead-free process | 升温速度 heat up speed(217℃到最高值) : 最 大 3℃/秒; 维持温度 keep temperature 在 175(±25)℃: 不超过 180 秒; 维持温度 keep temperature 在 217℃以上: 60-120 秒 最高温度限制范围maximum temperature: 255℃+0/-5℃; 维持keep在255℃+0/-5℃时间: 5-10秒; 降温速度cooling rate: 最大6℃/秒 | ----- | MIL-STD-750D:2031.2 J-STD-020C |
| 可焊性试验 Weldability test | 焊锡温度 Soldering temperature T. sol= 235 ± 5℃; 浸入速度 Immersion speed: 25±2.5 mm/秒; 上锡率 ≥95% 焊盘面积; Tin loading rate ≥ 95% pad area Immersion time: 2 ± 0.5 seconds | 浸入时间 Immersion time: 2± 0.5 秒 | MIL-STD-202F:208D MIL-STD-750D:2026 MIL-STD-883D:2003 IEC 68 Part 2-20 JIS C 7021:A-2 | |

外形尺寸

Outline Dimension



注 (Note) :

1. 单位 : 毫米 (mm) Unit: mm
2. 公差 : 如无特别标注则为± 0.1 mm

Tolerances: ± 0.1 mm if unmarked.

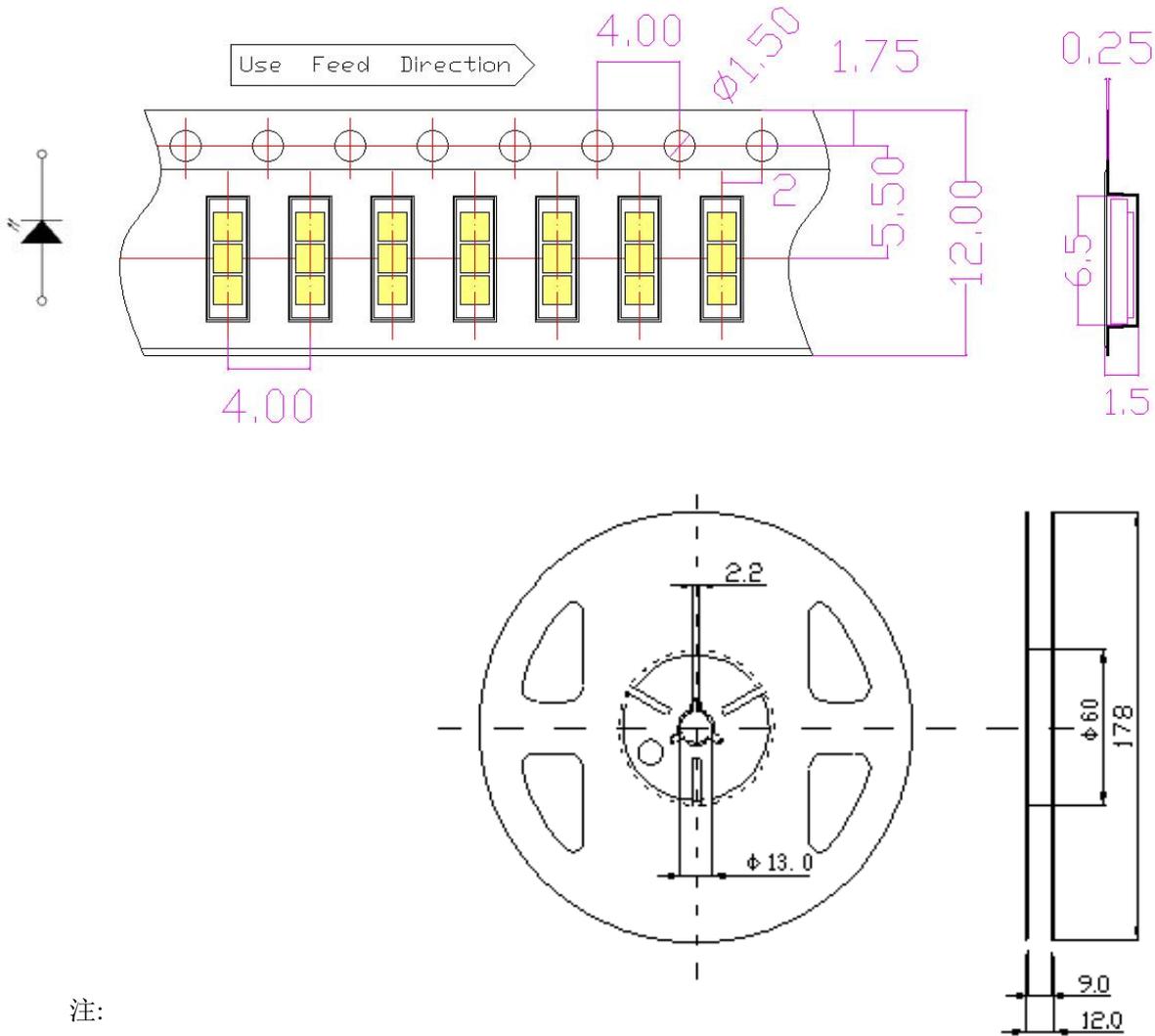
3.在不影响电路配置时, 建议增加中间焊盘覆铜区域, 或中间焊盘和负极焊盘连接, 能提高产品散热性能。建议使用热电分离的铜基板作为散热基板。建议使用钢网厚度为0.6-1mm

When the circuit configuration is not affected, it is recommended to increase the copper clad area of the intermediate pad or the connection between the intermediate pad and the negative pad, which can improve the product quality.Performance. It is recommended to use copper substrate with thermoelectric separation as heat dissipation substrate. It is recommended to use steel mesh with a thickness of 0.6-1mm.

包装 (1)

Packaging (1)

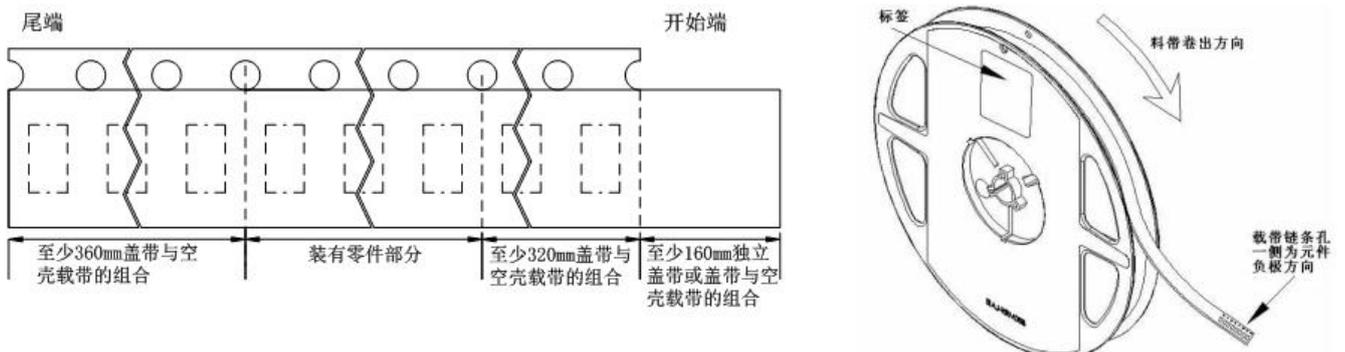
载带与圆盘尺寸 Belt and disk dimensions



注:

1. 尺寸单位为毫米(mm)。
1. Size unit is mm (mm).
2. 尺寸公差是±0.1mm。
2. The dimensional tolerance is ± 0.1mm.

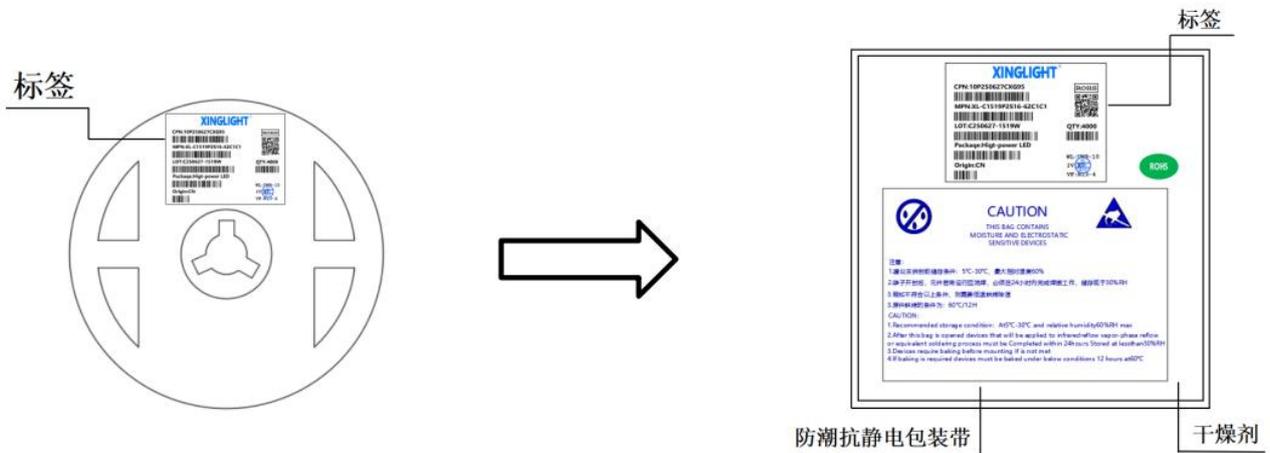
◆ 圆盘及载带卷出方向及空穴规格 Disk and carrier belt direction of roll and hole dimensions



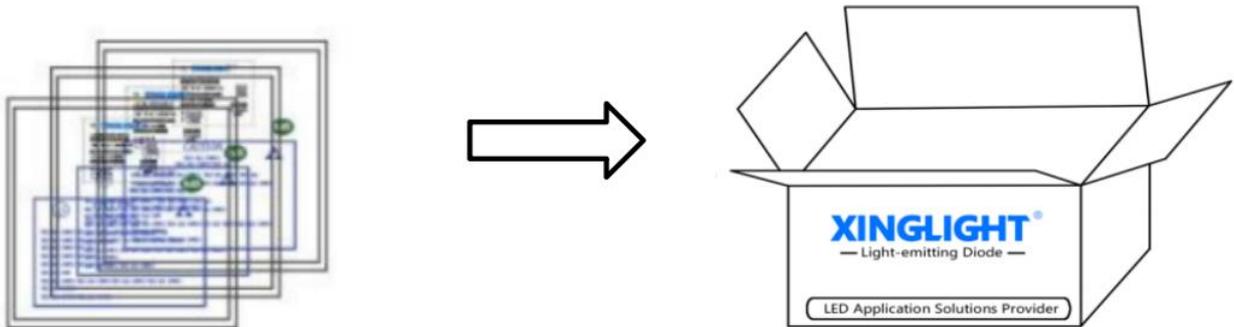
包装 (2)

Packaging (2)

◇ 防潮防静电包装 Moisture Proof and Antti-Electrostatic Foil Bag



◇ 外包装箱 Cardboard Box



◇ 标签说明 Label Expantion

| | |
|-------------|--------------|
| CPN: 批号/档位 | LOT: 日期/封装颜色 |
| MPN: 型号 | VF: 电压代码 |
| WL: 波长代码 | IV: 亮度代码 |
| ORIGIN: 产地 | QTY: 数量 |
| PACKAQE: 封装 | |



焊接指导 (1)

Guideline for Soldering (I)

1. 使用烙铁人手焊接

Hand Soldering

只建议在修理和重工的情况下使用手工焊接；推荐使用功率低于 30 W 的烙铁，焊接时烙铁的温度必须保持在 300℃ 以下，且每个电极只能进行一次焊接，每次焊接的持续时间不得超过 3 秒。

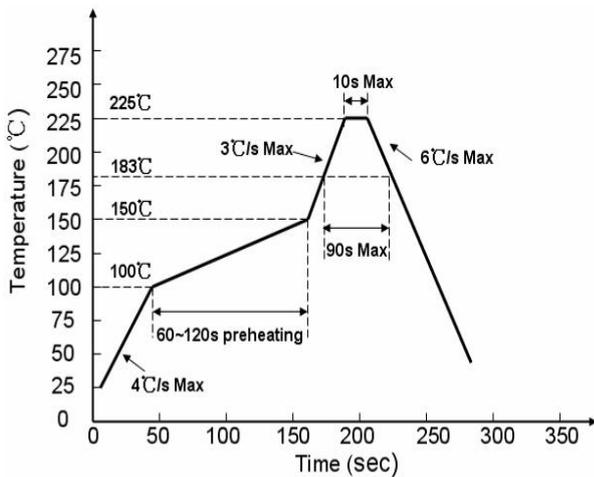
人手焊接过程中的不慎操作易引起 LED 产品的损坏，应当小心谨慎。

Manual welding is recommended only for repair and heavy industry situations. A soldering iron of less than 30W is recommended to be used in Hand Soldering. Please keep the temperature of the soldering iron under 300°C while soldering. Each terminal of the LED is to go for less than 3 second and for one time only.

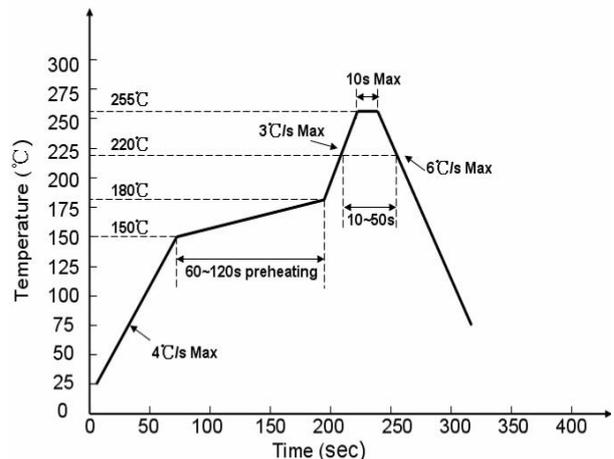
Be careful because the damage of the product is often started at the time of the hand soldering.

2. 回流焊接： 推荐使用以下无铅回流焊接温度图进行。

Reflow Soldering: Use the conditions shown in the under Figure of Pb -Free Reflow Soldering.



有铅制程 Lead process



无铅制程 lead free

回流焊接最多只能进行两次。

Reflow soldering should not be done more than two times.

在回流焊接升温过程中，请不要对 LED 施加任何压力。

Stress on the LEDs should be avoided during heating in soldering process.

在焊接完成后，待产品温度下降到室温之后，再进行其他处理。

After soldering, do not deal with the product before its temperature drop down to room temperature.

产品最佳的最高焊接温度建议控制在 $240 \pm 5^\circ\text{C}/6\text{S}$

The recommended maximum welding temperature for the product is $240 \pm 5^\circ\text{C}/6\text{s}$

焊接指导 (2)

Guideline for Soldering (2)

3. 清洗:

Cleaning

在焊接后推荐使用酒精进行清洗，在温度不高于 30°C 的条件下持续 3 分钟，不高于 50°C 的条件下持续 30 秒。

使用其他类似溶剂清洗前，请先确认使用的溶剂不会对 LED 的封装和环氧树脂部分造成损伤。超声波清洗也是有效的方法，一般最大功率不应超过 300W，否则可能对 LED 造成损伤。请根据具体的情况预先测试清洗条件是否会对 LED 造成损伤。

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30°C for 3 minutes or 50°C for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pretest should be done to confirm whether any damage to LEDs will occur.

*** 注意：** 此一般指导原则并不适用于所有 PCB 设计和焊接设备的配置。具体工艺受到诸多因素的影响，请根据特定的 PCB 设计和焊接设备来确定焊接方案。

*** Note:** This general guideline may not apply to all PCB designs and configurations of all soldering equipment. The technics in practise is influenced by many factors, it should be specialized base on the PCB designs and configurations of the soldering equipment..

使用注意事项（1）

Precautions (1)**1. 贮存:****Storage**

- 本产品使用密封防潮抗静电袋包装，并附有干燥剂，未开封的产品有一年的保存时间。

Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to a minimum.

- 开封前，产品须存放在温度不高于 30℃，湿度不高于 60%RH 的环境中。

Before opening the package, the product should be kept at 30℃ or less and humidity less than 60% RH, and be used within a year.

- 开封后，产品须存放在温度不高于 30℃，湿度不高于 40%RH 的环境中，且应该在 168 小时（7 天）内使用完。建议工作环境为温度不高于 30℃，湿度不高于 60%RH。

After opening the package, the product should be stored at 30℃ or less and humidity less than 40%RH, and be soldered within 168 hours (7 days). It is recommended that the product be operated at the workshop condition of 30℃ or less and humidity less than 60%RH.

- 对于尚未焊接的 LED，如果吸湿剂或包装失效，或者产品没有符合以上有效存储条件，烘焙可以起到一定的性能恢复效果。烘焙条件：60±5℃，持续24 小时。

If the moisture absorbent material has fade away or the LEDs have exceeded the storage time, baking treatment should be performed based on the following condition: (60±5)℃ for 24 hours.

2. 静电:**Static Electricity**

静电和电涌会导致产品特性发生改变，例如正向电压降低等，如果情况严重甚至会损毁产品。所以在使用时必须采取有效的防静电措施。所有相关的设备和机器都应该正确接地，同时必须采取其他防止静电和电涌的措施。使用防静电手环，防静电垫子，防静电工作服、工作鞋、手套，防静电容器，都是有效的防止静电和电涌的措施。

Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristic such as the forward voltage becomes lower, or the LEDs do not light at the low current. even not light.

All devices, equipment and machinery must be properly grounded. At the same time, it is recommended that wrist bands or anti-electrostatic gloves, anti-electrostatic containers be used when dealing with the LEDs.

使用注意事项 (2)

Precautions (2)

3. 温度控制:

temperature Control

为确保在组装时降低接触热阻, 请注意在组装过程中, 散热片采用良好品质的导热膏涂布均匀且分布面积合理, 不可出现太少或高低不平等现象。散热介质需保证电介质耐压测试至少通过 500V。

During assembly, please ensure that a good quality thermal paste is applied and distributed evenly over the surface. While using thermal pad (Heat Sink), make sure LED is firmly tightened and there is no gap between surfaces. The need to ensure the cooling medium dielectric withstand test at least through 500V.

4. 驱动控制:

drive control

本产品需使用恒流源进行驱动, 且输出电流符合规格书上的功率使用范围, 如需使用恒压源或其他使用条件, 请进行使用效果风险评估。

Drive this product at constant current. Output current range specifications should be according to the operational and other conditions, as mentioned in data sheet. Before using a constant voltage source or altered specifications, other than recommended, please consider risk factors.

LED 的特性容易因为自身的发热和环境的温度的改变而发生改变。温度的升高会降低 LED 的发光效率、影响发光颜色等, 所以在设计时应充分考虑散热的问题。

Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color changed and so on. Please consider the heat generation of the LEDs when making the system design.

使用注意事项 (3)

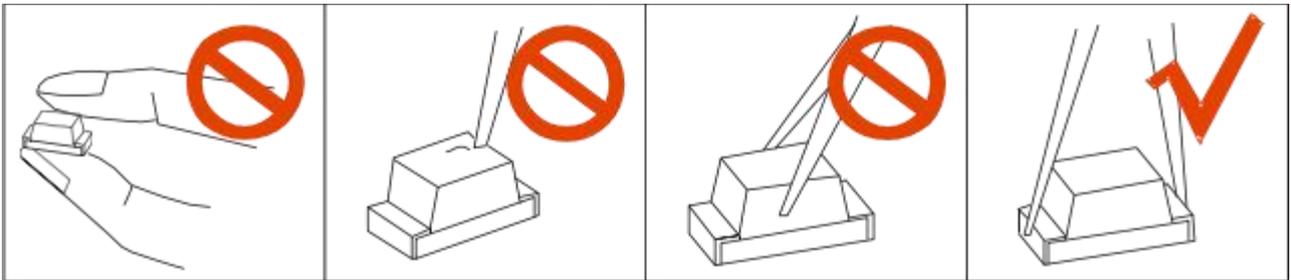
Precautions (3)

4. 其他事项:

Others

直接用手拿取产品不但会污染封装树脂表面,也可能由于静电等因素导致产品性能的改变。过度的压力也可能直接影响封装内部的管芯和金线,因此请勿对产品施加过度压力,特别当产品处于高温状态下,例如在回流焊接过程中。

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED 的环氧树脂封装部分相当脆弱,请勿用坚硬、尖锐的物体刮、擦封装树脂部分。在用镊子夹取的时候也应当小心注意。

The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface.

While handling the product with tweezers, do not hold by the epoxy resin, be careful.

5. 眼睛保护忠告:

Safety Advice For Human Eyes

LED 发光时,请勿直视发光光源,特别是对于一些光强较高的 LED,强光可能伤害你的眼睛。

Viewing direct to the light emitting center of the LEDs, especially those of great Luminous Intensity, will cause great hazard to human eyes. Please be careful.

规格书如有修改,不另行通知

If there are any modifications to the specification sheet, no further notice will be given